

DATE 28 JUN 2007

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- DIMENSIONING AND TOLERANGING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS. DIMENSION 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN
- 0.15 AND 0.30 MM FROM TERMINAL TIP. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
Α	0.50	0.60
A1	0.00	0.05
b	0.20	0.30
D	3.00 BSC	
D2	2.60	2.80
E	3.00 BSC	

1.90 2.10 e K 0.50 BSC 0.20 L 0.25 0.35

GENERIC MARKING DIAGRAM*



Α = Assembly Location

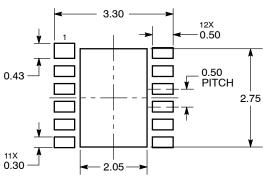
L = Wafer Lot Υ = Year W = Work Week

= Pb-Free Package

(Note: Microdot may be in either location) *This information is generic. Please refer to

device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	12 PIN LLGA, 3 X 3 X 0.55T, 0.5P		PAGE 1 OF 1

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